

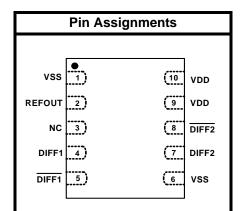
# CRYSTAL-LESS PCI-EXPRESS GEN 1 & GEN 2 DUAL OUTPUT CLOCK GENERATOR

#### **Features**

- Crystal-less clock generator with integrated CMEMS
- PCI-Express Gen 1/2 compliant
- Two PCIe 100 MHz differential HCSL outputs
- One 25 MHz single-ended LVCMOS output
- Supports Serial (ATA) at 100 MHz
- Low power differential output buffers
- No termination resistors required for differential output clocks

- Triangular spread spectrum profile for maximum EMI reduction (Si50122-A4)
- Industrial Temperature –40 to 85 °C
- 2.5 V, 3.3 V Power supply
- Small package 10-pin TDFN (2.0x2.5 mm)
- Si50122-A3 does not support spread spectrum outputs
- Si50122-A4 supports 0.5% down spread outputs





Patents pending

#### **Applications**

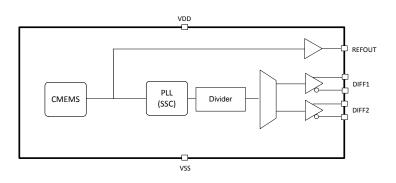
- Digital TV
- Set top box
- Solid State Drives (SSD)
- Wireless Access Point
- Home Gateway

- Network Attached Storage
- Multi-function Printer
- Wireless Access Point
- Digital Video Cameras

#### **Description**

Si50122-A3/A4 is a high performance, crystal-less PCIe clock generator that can generate two 100 MHz PCIe clock and one 25 MHz LVCMOS clock outputs. The differential clock outputs are compliant to PCIe Gen1 and Gen 2 specifications. The ultra-small footprint (2.0x2.5 mm) and industry leading low power consumption make Si50122-A3/A4 the ideal clock solution for consumer and embedded applications where board space is limited and low power is needed.

#### **Functional Block Diagram**





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## 1. Electrical Specifications

**Table 1. Recommended Operating Conditions** 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Supply Voltage (3.3 V Supply)	$V_{DD}$	3.3 V ± 10%	2.97	3.3	3.63	V
Supply Voltage (2.5 V Supply)	V <sub>DD</sub>	2.5 V ± 10%	2.25	2.5	2.75	V

### **Table 2. DC Electrical Specifications**

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Operating Voltage <sub>VDD=3.3 V</sub>	$V_{DD}$	3.3 V ± 10%	2.97	3.30	3.63	V
Operating Voltage <sub>VDD=2.5 V</sub>	$V_{DD}$	2.5 V ± 10%	2.25	2.5	2.75	V
Operating Supply Current	I <sub>DD</sub>	Full active; 3.3 V ± 10%	_	20	23	mA
		Full active; 2.5 V ± 10%	_	18	21	mA
Input Pin Capacitance	C <sub>IN</sub>	Input Pin Capacitance	_	3	5	pF
Output Pin Capacitance	C <sub>OUT</sub>	Output Pin Capacitance		_	5	pF



**Table 3. AC Electrical Specifications** 

Parameter	Symbol	Condition	Min	Тур	Max	Unit
DIFF Clocks			_		I.	
Duty Cycle	T <sub>DC</sub>	Measured at 0 V differential	45	_	55	%
Skew	T <sub>SKEW</sub>	Measured at 0 V differential	_	_	100	ps
Output Frequency	F <sub>OUT</sub>	VDD = 3.3 V	_	100	_	MHz
Frequency Accuracy	F <sub>ACC</sub>	All output clocks	_	_	100	ppm
Slew Rate	t <sub>r/f2</sub>	Measured differentially from ±150 mV	0.6	_	5.0	V/ns
Crossing Point Voltage at 0.7 V Swing	V <sub>OX</sub>		300	_	550	mV
Voltage High	$V_{HIGH}$		_	_	1.15	V
Voltage Low	$V_{LOW}$		-0.3	_	_	V
Spread Range	S <sub>RNG</sub>	Down Spread, -A4 only	_	_	-0.5	%
Modulation Frequency	F <sub>MOD</sub>	–A4 only	30	31.5	33	kHz
DIFF Clocks Jitter Parameters,	VDD = 3.3 V	± 10%		JI.	•	
PCle Gen1 Pk-Pk	Pk-Pk <sub>GEN1</sub>	PCIe Gen 1	_	20.7	35	ps
PCle Gen2 Phase Jitter	RMS <sub>GEN2</sub>	10 kHZ < F < 1.5 MHz	_	0.8	2.1	ps
		1.5 MHZ < F < Nyquist	_	1.4	2.2	ps
DIFF Clocks Jitter Parameters,	VDD = 2.5V :	± 10%	•		•	
PCle Gen1 Pk-Pk	Pk-Pk <sub>GEN1</sub>	PCIe Gen 1	_	25	40	ps
PCle Gen2 Phase Jitter	RMS <sub>GEN2</sub>	10 kHZ < F < 1.5 MHz	_	0.9	2.9	ps
		1.5 MHZ < F < Nyquist	_	1.7	3.0	ps
25 MHz at 3.3 V			•		•	
Duty Cycle	T <sub>DC</sub>	Measurement at 1.5 V	45	_	55	%
Output Rise Time	t <sub>r</sub>	C <sub>L</sub> = 10 pF, 20% to 80%		1.2	3.0	ns
Output Fall Time	t <sub>f</sub>	C <sub>L</sub> = 10 pF, 20% to 80%		1.2	3.0	ns
Cycle to Cycle Jitter	T <sub>CCJ</sub>	Measurement at 1.5 V	_	_	250	ps
Long Term Accuracy	L <sub>ACC</sub>	Measured at 1.5 V	<u> </u>	<u> </u>	100	ppm
Powerup Time	1		1	1	<u> </u>	
Clock Stabilization from Powerup	T <sub>STABLE</sub>	First powerup to first output	_	_	10	ms
Note: Visit www.pcisig.com for compl	l l	fications.	1	1	l	

## Si50122-A3/A4

**Table 4. Thermal Conditions** 

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Temperature, Storage	T <sub>S</sub>	Non-functional	-65		150	°C
Temperature, Operating Ambient	T <sub>A</sub>	Functional	-40		85	°C
Temperature, Junction	TJ	Functional	_		150	°C
Dissipation, Junction to Case	Ø <sub>JC</sub>	JEDEC (JESD 51)	_		38.3	°C/W
Dissipation, Junction to Ambient	Ø <sub>JA</sub>	JEDEC (JESD 51)	_		90.4	°C/W

#### **Table 5. Absolute Maximum Conditions**

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Main Supply Voltage	V <sub>DD_3.3V</sub>				4.6	V
Input Voltage	V <sub>IN</sub>	Relative to V <sub>SS</sub>	-0.5		4.6	$V_{DC}$
ESD Protection (Human Body Model)	ESD <sub>HBM</sub>	JEDEC (JESD 22 - A114)	2000		_	V
Flammability Rating	UL-94	UL (Class)		V-0		

**Note:** While using multiple power supplies, the voltage on any input or I/O pin cannot exceed the power pin during powerup. Power supply sequencing is NOT required.

## 2. Test and Measurement Setup

Figures 1–3 show the test load configuration for the differential clock signals.

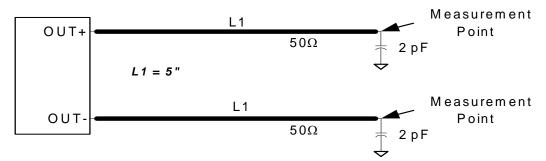


Figure 1. 0.7 V Differential Load Configuration

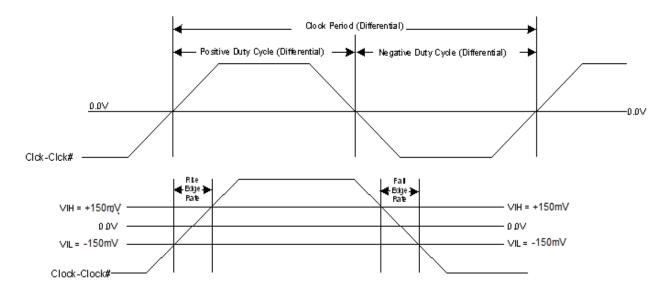


Figure 2. Differential Measurement for Differential Output Signals (for AC Parameters Measurement)

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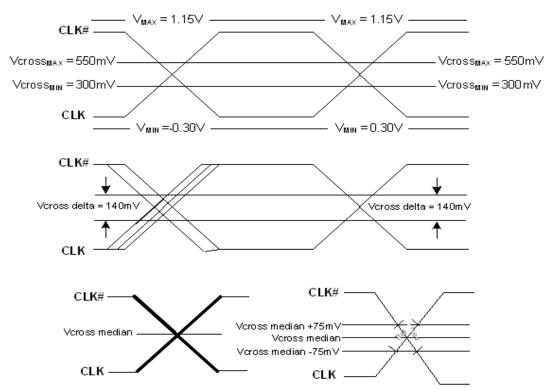


Figure 3. Single-ended Measurement for Differential Output Signals (for AC Parameters Measurement)

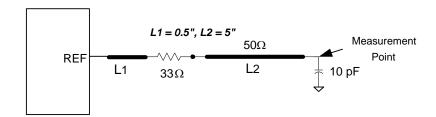


Figure 4. Single-ended Clocks with Single Load Configuration

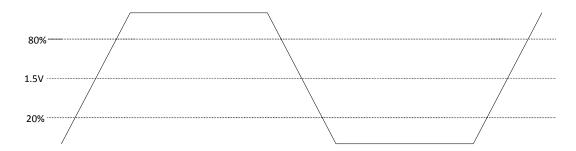


Figure 5. Single-ended Output Signal (for AC Parameter Measurement)

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## 3. Pin Descriptions

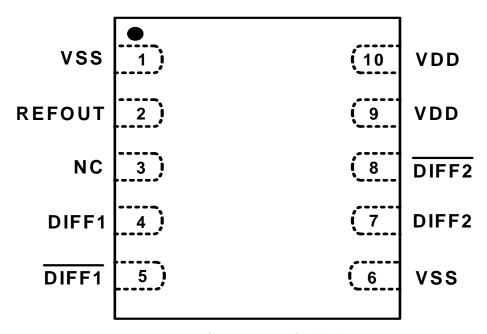


Figure 6. 10-Pin TDFN

Table 6. Si50122-Ax-GM 10-Pin TDFN Descriptions

Pin#	Name	Туре	Description
1	VSS	GND	Connect to Ground
2	REFOUT	O, SE	25 MHz LVCMOS clock output
3	NC	NC	No Connect. Do not connect this pin to anything.
4	DIFF1	O, DIF	0.7 V, 100 MHz differential clock output
5	DIFF1	O, DIF	0.7 V, 100 MHz differential clock output
6	VSS	GND	Connect to Ground
7	DIFF2	O, DIF	0.7 V, 100 MHz differential clock output
8	DIFF2	O, DIF	0.7 V, 100 MHz differential clock output
9	VDD	PWR	Power supply
10	VDD	PWR	Power supply

## 4. Ordering Guide

Part Number	Spread Option	Package Type	Temperature
Si50122-A3-GM	No Spread	10-pin TDFN	Industrial, -40 to 85 °C
Si50122-A3-GMR	No Spread	10-pin TDFN—Tape and Reel	Industrial, -40 to 85 °C
Si50122-A4-GM	-0.5% Spread	10-pin TDFN	Industrial, -40 to 85 °C
Si50122-A4-GMR	-0.5% Spread	10-pin TDFN—Tape and Reel	Industrial, -40 to 85 °C

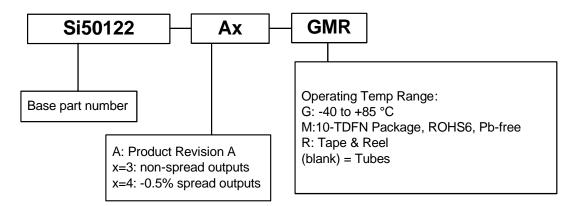


Figure 7. Ordering Information



## 5. Package Outlines

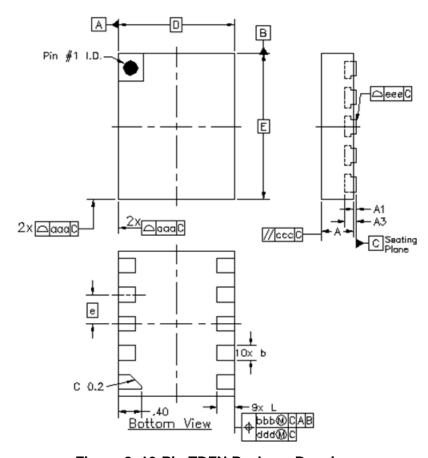


Figure 8. 10-Pin TDFN Package Drawing

**Table 7. Package Diagram Dimensions** 

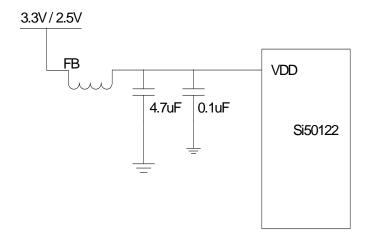
Symbol	Min	Nom	Max				
А	0.80 0.85		0.90				
A1	0.00	0.05					
А3		0.203 REF					
b	0.20	0.25	0.30				
D		2.00 BSC					
е	0.50 BSC						
E		2.50 BSC					
L	0.35	0.4	0.45				
aaa		0.10					
bbb		0.10					
ссс	0.10						
ddd		0.05					
eee		0.08					

#### Notes:

- 1. All dimensions shown are in millimeters (mm) unless otherwise noted.
- 2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.



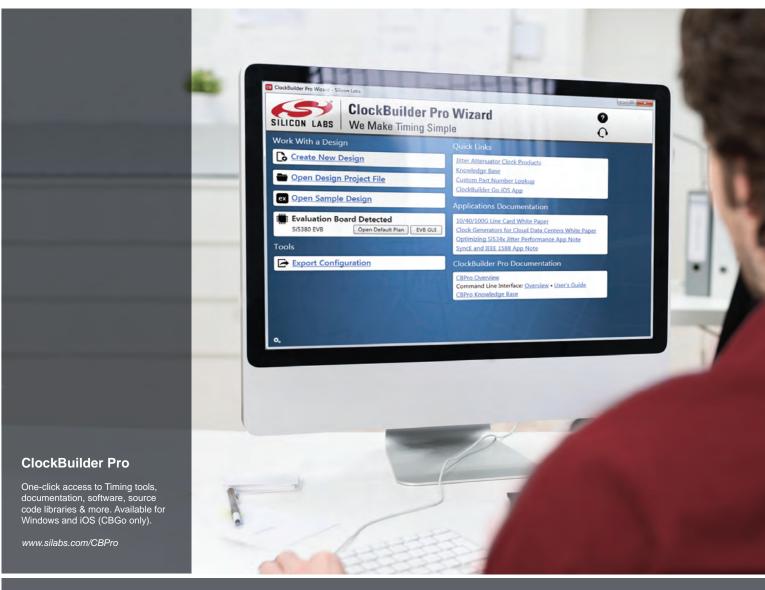
## 6. Recommended Design Guideline



Note: FB Specifications: DC resistance 0.1–0.3  $\Omega$ 

Impedance at 100 MHz  $\geq$  1000  $\Omega$ 

Figure 9. Recommended Application Schematic











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